





Features:

MEMS Technology

- Direct pin to pin drop-in replacement for industry-standard packages
- 0.6 pSec RMS phase jitter (random) over 12 kHz to 20 MHz bandwidth
- LVPECL and LVDS output signaling types
- Industry-standard package 3.2 x 2.5, and 5.0 x 3.2 mm x mm
- Pb-free, RoHS and REACH compliant
- Electronic Specification

Typical Applications:

- Fibre Channel
- Server and Storage
- GPON, EPON
- 100M / 1G /10G Ethernet

| Electronic Specifications: | | |
|--------------------------------------|---|--|
| Frequency Range | 220.000 MHz to 625.000 MHz | |
| Frequency Stability | See Part Number Guide | Inclusive of all changes in Operating Temp. Range, Load, and Voltage |
| First Year Aging | ±2.0 ppm max | +25°C ±2.0°C |
| 10 Years Aging | ±5.0 ppm max | +25°C ±2.0°C |
| Operating Temperature | See Part Number Guide | |
| Supply Voltage (Vdd) ±10% | See Part Number Guide | |
| Input Voltage High | 70% of Vdd min | Pin 1, OE or ST |
| Input Voltage Low | 30% of Vdd max | Pin 1, OE or ST |
| Input Pull-up Impedance | 100 kΩ typ., 250 kΩ max 2.0 MΩ min | Pin 1, OE logic high or logic low, or \overline{ST} logic high Pin 1, \overline{ST} logic low |
| Start-up Time | 6.0 mSec typ., 10.0 mSec max | Measured from the time Vdd reaches its rated minimum values |
| Resume Time | 6.0 mSec typ., 10.0 mSec max | Measured from the time $\overline{\text{ST}}$ pin crosses 50% threshold. |
| Symmetry | 45%/55% | |
| LVPECL, DC and AC Characterist | ics | |
| Current Consumption | 61 mA typ., 69 mA max | Excluding Load Termination Current, Vdd = +3.3 V or +2.5 V |
| OE Disable Supply Currrent | 35 mA max | OE = Low |
| Output Disable Leakage Current | 1 μA max | OE = Low |
| Standby Current | 100 μA max | \overline{ST} = Low, for all Vdds |
| Maximum Output Current | 30 mA max | Max average current drawn from OUT+ or OUT- |
| Logic "1" | Vdd -1.1 min / Vdd – 0.7 max | See figure 1(a) |
| Logic "0" | Vdd -1.9 min / Vdd – 1.5 max | See figure 1(a) |
| Output Differential Voltage Swing | 1.2 V min. 1.6V typ., 2.0 V max | See figure 1(b) |
| Rise/Fall Time | 300 pSec typ., 500 pSec max | 20% to 80%, see figure 1(a) |
| OE Enable/Disable Time | 115 nSec max | F = 220.00 MHz – For other frequencies, T_oe = 100nSec + 3 period |
| RMS Period Jitter | 1.2 pSec typ., 1.7 pSec max 1.2 pSec typ., 1.7 pSec max 1.2 pSec typ., 1.7 pSec max | F = 266.00 MHz, Vdd = +3.3 V or +2.5 V F = 312.50 MHz, Vdd = +3.3 V or +2.5 V F = 622.08 MHz, Vdd = +3.3 V or +2.5 V |
| RMS Phase Jitter (random) | 0.60 pSec typ, 0.85 pSec max. | F = 312.50 MHz, Integration Bandwidth = 12 kHz to 20 MHz all Vdds |
| LVDS, DC and AC Characteristics | | _ |
| Current Consumption | 47 mA typ., 55 mA max | Excluding Load Termination Current, Vdd = +3.3 V or +2.5 V |
| OE Disable Supply Current | 35 mA max | OE = Low |
| Differential Output Voltage | 250 mV min, 350 mA typ. 450 mV max | See Figure 2 |
| Output Disable Leakage Current | 1 μA max | OE = Low |
| Standby Current | 100 µA max | $\overline{\text{ST}}$ = Low, for all Vdds |
| VOD Magnitude Change | 50 mV max | See Figure 2 |
| Offset Voltage | 1.125 mV min, 1.200 mV typ., 1.375 mV max | See Figure 2 |
| VOS Magnitude Change | 50 mV max | See Figure 2 |
| Rise/Fall Time | 495 pSec typ., 600 pSec max | 20% to 80%, See Figure 2 |
| OE Enable Time/Disable Time | 115 nSec max | F = 220.00 MHz, For other Frequencies, T_oe=100nSec + 3 period |
| RMS Period Jitter | 1.4 pSec typ,. 1.7 pSec max 1.4 pSec typ,. 1.7 pSec max 1.2 pSec typ,. 1.7 pSec max | F = 266.00 MHz, Vdd = +3.3 V or +2.5 V F = 312.50 MHz, Vdd = +3.3 V or +2.5 V F = 622.08 MHz, Vdd = +3.3 V or +2.5 V |
| RMS Phase Jitter (random) | 0.60 pSec typ., 0.85 pSec max | F = 312.50 MHz, Integration Bandwidth = 12 kHz to 20 MHz all Vdds |
| Notes: | | |

Notes:

• All min and max limits are specified over temperature and rated operating voltage with 15pF output unless otherwise stated.

• Typical values are at +25°C and nominal supply voltage.







Ordering Information:

| Part Number Guide | | | | | | | |
|--|--------------------------|--|---|------------------------|------------------------------|-------------|--|
| Packages | Input Voltage | Operating Temperature | Stability (ppm) | Output | Select Function | Frequency | |
| IM841B – 5.0 x 3.2 IM841C – 3.2 x 2.5 | 6 = +2.5 V 3 = +3.3 V | 1 = 0°C to +70°C 2 = -40°C to +85°C 3 = -20°C to +70°C | E = ±10 F = ±20 A = ±25 Z = ±30 B = ±50 | 8 = LVDS 9 = LVPECL | H = Tri-state S = Standby | - Frequency | |

Sample Part Number: IM841C-62F9S-100.0000MHz

This 100.0000 MHz oscillator in a 3.2 x 2.5 package with stability ±20 ppm from -40°C to +85°C using a supply voltage of +2.5 V. With an output waveform of LCPECL and Pin 1 functioning as Standby

Sample Part Number: IM841B-33Z8H-150.0000MHz

This 150.0000 MHz oscillator in a 5.0 x 3.2 package with stability ±30 ppm from -20°C to +70°C using a supply voltage of +3.3 V. With an output waveform of LVDS and Pin 1 functioning as Tri-state.

Notes:

- Not all options are available at all frequencies and temperatures ranges.
- Please consult with sales department for any other parameters or options.
- Oscillator specification subject to change without notice.

| Absolute Maximum Limits | | | | | | |
|---|---------------------|--|--|--|--|--|
| Storage Temperature | -65°C to +150°C | | | | | |
| Supply Voltage (Vdd) | -0.5 VDC to 4.0 VDC | | | | | |
| Electrostatic Discharge | 2000 V max | | | | | |
| Solder Temperature (follow standard Pb free soldering guidelines) | 260°C max | | | | | |
| Junction Temperature | 150°C max | | | | | |





Waveform Diagrams:

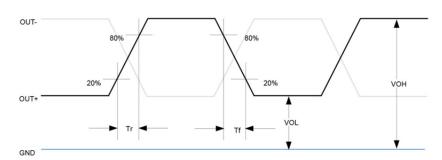


Figure 1(a): LVPECL Voltage Levels per Differential Pin (OUT+/OUT-)

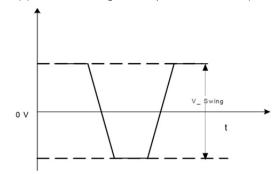


Figure 1(b): LVPECL Voltage Levels Across Differential Pair

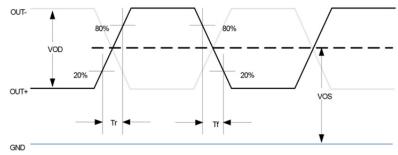
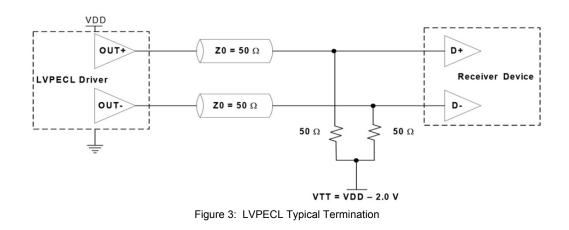


Figure 2: LVDS Voltage Levels per Differential Pin (OUT+/OUT-)

Termination Diagrams – LVPECL:



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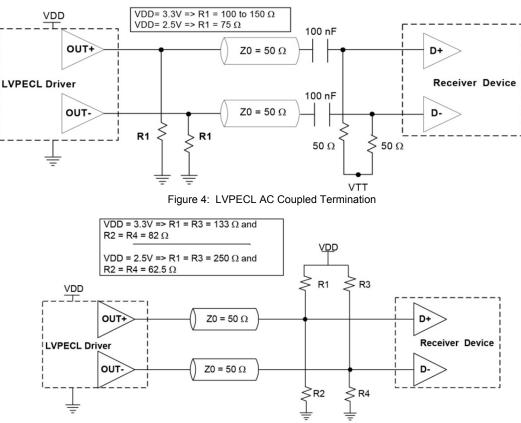
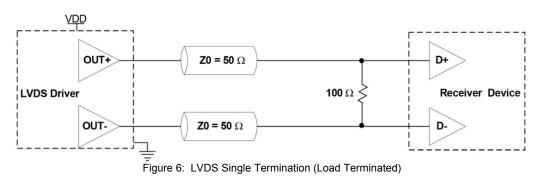


Figure 5: LVPECL with Thevenin Typical Termination

Termination Diagram – LVDS:



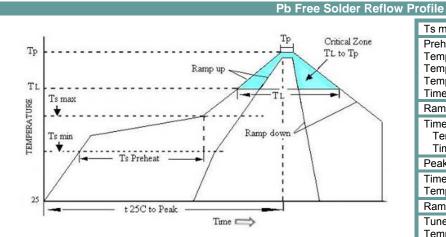






Environmental Specifications:

| Environmental Compliance | | | | | | |
|----------------------------|---------------------------|--|--|--|--|--|
| Parameter | Condition/Test Method | | | | | |
| Mechanical Shock | MIL-STD-883F, Method 2002 | | | | | |
| Mechanical Vibration | MIL-STD-883F, Method 2007 | | | | | |
| Temperature Cycle | JESD22, Method A104 | | | | | |
| Solderability | MIL-STD-883F, Method 2003 | | | | | |
| Moisture Sensitivity Level | MSL Level 1 at +260°C | | | | | |



Units are backward compatible with +240°C reflow processes

| Ts max to T _L (Ramp-up Rate) | 3°C / second max | | |
|--|---|--|--|
| Preheat Temperature min (Ts min) Temperature typ (Ts typ) Temperature max (Ts max) Time (Ts) | 150°C 175°C 200°C 60 to180 seconds | | |
| Ramp-up Tate (T _L to Tp | 3°C / second max | | |
| Time Maintained Above Temperature (T_L) Time (T_L) | 217°C 60 to 150 seconds | | |
| Peak Temperature (Tp) | 260°C max for seconds | | |
| Time within 5°C to Peak Temperature (Tp) | 20 to 40 seconds | | |
| Ramp-down Rate | 6°C / second max | | |
| Tune 25°C to Peak Temperature | 8 minute max | | |
| Moisture Sensitivity Level (MSL) | Level 1 | | |

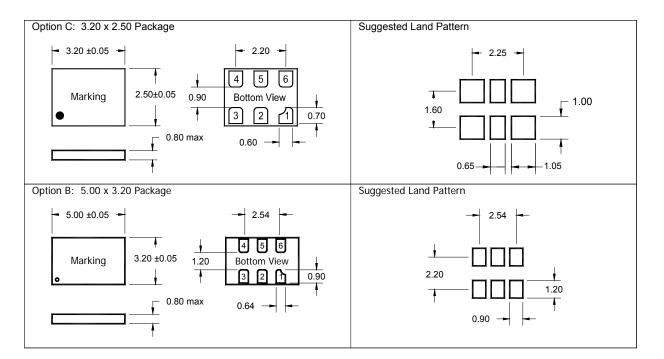






Mechanical Details:

Package Dimensions and Suggested Land Pattern



Marking

Line 1 = XXXXX (Lot code) Dot to denote Pin 1 location Package Information

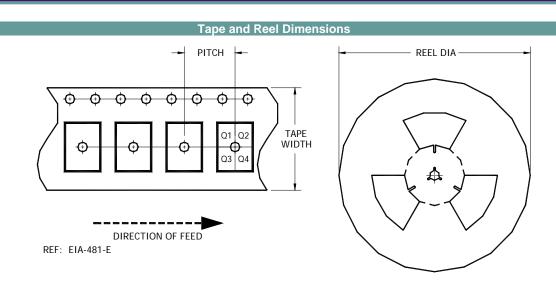
Leadframe: C194 Plating: NiPdAu

Pin Functionally:

| Pin | Symbol | | Functionality | Pi | n Assignme | nts | |
|-------|--------------|------------------|---|------------|------------|-----|------|
| 1 | OE | Tri-state | High or Open = specified frequency output Low = Output is high impedance, only output is disabled. | | | | |
| | ST | Standby | High or Open = specified frequency output. Low = Output is low (weak pull down). Device goes to sleep mode. Supply current reduces to standby current. | OF | | | |
| 2 | NC | NA | No Connection: Leave it floating or connected to GND for better head dissipation | OE ST 1 | | 6 | Vdd |
| 3 | GND | Power | Vdd – Power Supply Ground | N/C 2 | Top View | 5 | OUT- |
| 4 | Out+ | Output | Oscillator output | | | | |
| 5 | Out- | Output | Complementary Oscillator output | GND 3 | l . | 4 | OUT+ |
| 6 | Vcc | Power | Power supply voltage | | | | 0011 |
| Notes | - | | | | | | |
| e | xternally dr | iven. If Pin 1 r | p resistor of 10.0 kΩ or less is recommended if Pin 1 is not needs to be left floating, use the NC option. For higher between Pin 4 (Vcc) and Pin 1 (GND) is required. | | | | |







| Part Number | Size | Pitch | Tape Width | Pin Orient. | Reel Dia. | Count |
|----------------|-----------|---------------|---------------|----------------|--------------|-------|
| IM841B | 5.0 x 3.2 | 4.0 ± 0.1 | 8.3 max | Q1 | 180 Dia | 3000 |
| IM841C | 3.2 x 2.5 | 4.0 ± 0.1 | 8.3 max | Q1 | 180 Dia | 3000 |

Notes:`

- All dimensions are in mm.
- Do not scale drawings.

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